

Title (en)

ELECTROMAGNETIC WAVE IRRADIATION MOLDING DEVICE AND ELECTROMAGNETIC WAVE IRRADIATION MOLDING METHOD

Title (de)

VORRICHTUNG ZUR STRAHLFORMUNG ELEKTROMAGNETISCHER WELLEN UND VERFAHREN ZUR STRAHLFORMUNG ELEKTROMAGNETISCHER WELLEN

Title (fr)

DISPOSITIF DE MOULAGE PAR IRRADIATION PAR ONDES ÉLECTROMAGNÉTIQUES ET PROCÉDÉ DE MOULAGE PAR IRRADIATION PAR ONDES ÉLECTROMAGNÉTIQUES

Publication

**EP 2722146 B1 20210127 (EN)**

Application

**EP 12799763 A 20120608**

Priority

- JP 2011135411 A 20110617
- JP 2012064770 W 20120608

Abstract (en)

[origin: EP2722146A1] An electromagnetic wave irradiation molding apparatus 1 includes a mold 2 made of an insulating material and electromagnetic wave irradiation means 4 for irradiating specific electromagnetic waves X including a wavelength region of 0.01 m to 100 m. The mold 2 is separated into mold parts 2A and 2B, between which a cavity 20 to be filled with a thermoplastic resin 6 is provided to form a molded article. A surface layer 3 having a capability to absorb the specific electromagnetic waves X is formed on at least a part of an inner wall surface of the cavity 20.

IPC 8 full level

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CPC (source: EP US)

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Cited by

JP2020183110A; EP3936299A4; JP2020183109A; US11117301B2

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